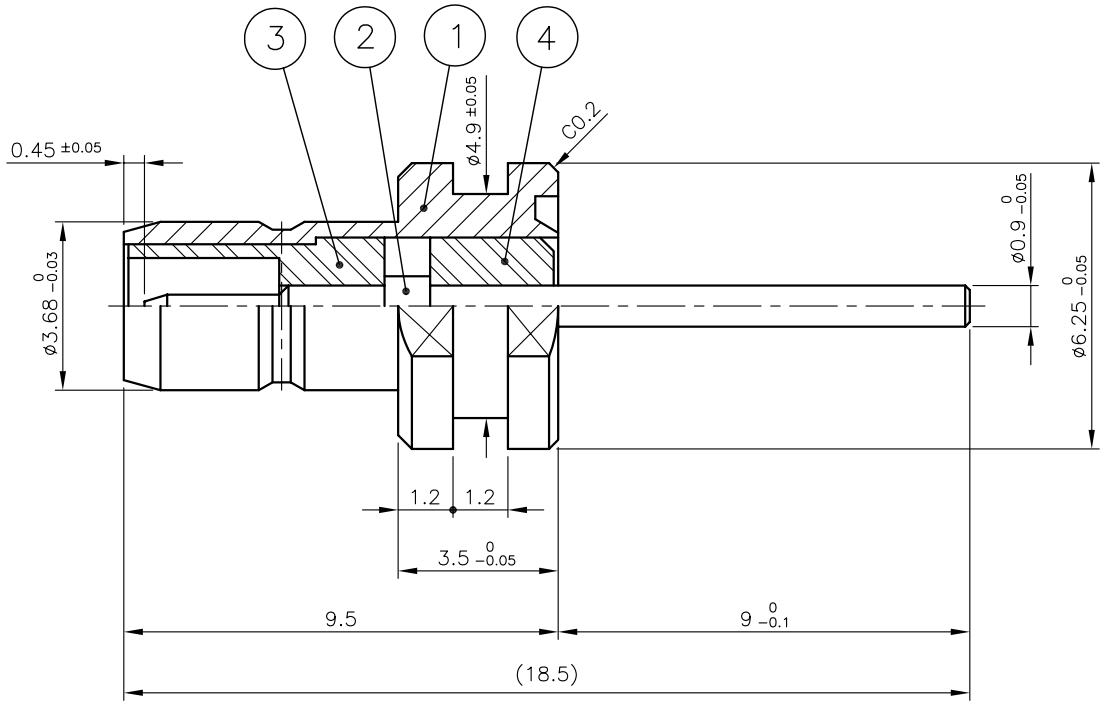
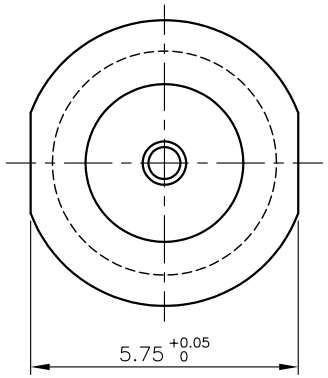
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration		C.Y.H.	2011.02.24.





Note.

1. 제품의 외관에 이상이 없을 것.
2. 본 부품은 MS201-02를 만족 할 것.
3. 도금 사양 Ni Plate 염수분무 96시간 +24시간 방치
   (ES96200-03 염수분무 시험 만족 할 것.)
4. CONTACT는 430°C에서 2시간 열처리 시간 준수 할 것.
5. 상대물과 삽입력과 이탈력
   - 삽입력 : 2~4kgf 이하
   - 이탈력 : 5~8kgf 이상

NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
4	INSULATOR	1	ACETAL	White	DIN01878-N/1
3	INSULATOR	1	ACETAL	White	DIN01877-N/1
2	CONTACT	1	MBsBD	Gold Plate 0.38μm	DCT02400-5/1
1	BODY	1	MBsBD	Nickel Plate 5μm	DBD02881-5/1

TOLERANCE	Decimal ±0.25	DATE	2011. 02. 24.
	Angle ±1°	APPROVED BY	Y.H.CHOI
		CHECKED BY	
MATERIAL	-	DRAWN BY	
FINISH	-	SCALE 6/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
Fax : 82-32-347-8017

TITLE: SMB50-J-BR

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